

1 Scope:

- 1.1 This specification is applicable to lead free and halogen free of RoHS directive for RTV series high voltage thick film chip resistors
- 1.2 The product is for general electronic purpose.

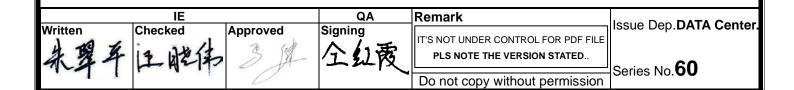
2 Explanation Of Part Numbers:

(EX)

	0 <u>60</u> 3	<u>100</u>	ٿ_		
Туре	Size	Nominal Resistance	Resistance Tolerance	Packaging(Refer to IE-SP-055)	
High Voltage Thick Film	1200	5% EX. 10Ω=100 (3-Digit) 4.7Ω=4R7	D=± 0.5%	H4 : 2 mm Pitch Carrier Tape 40000 pcs TP : 4 mm Pitch Carrier Tape 5000 pcs P2 : 4 mm Pitch Carrier Tape 10000 pcs P3 : 4 mm Pitch Carrier Tape 15000 pcs	
Chip Resistors	1210 2010 2512	0.5% 1% (4-Digit) EX. 10.2Ω=10R2 10KΩ=1002	─ F=± 1% J=± 5%	P3:4 mm Pitch Carrier Tape 15000 pcs P4:4 mm Pitch Carrier Tape 20000 pcs TE:4 mm Pitch Carrier Tape 4000 pcs BA:散裝(盒裝)	

3 General Specifications:

Rated Max. Max.				тор		Resistance Range				
Туре	Power at 70℃	Working Voltage	Overlo ad Voltage	T.C.R (ppm/℃)	D(±0.5%) E-96	F(±1%) E-96	J(±5%) E-24			
	4			±100	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$			
RTV0603	$\frac{1}{10}$ W	350V	500V	±200	1Ω≦R<10Ω	1Ω≦R<10Ω	1Ω≦R<10Ω			
	10			±200	$1M\Omega < R \leq 10M\Omega$	$1M\Omega < R \leq 10M\Omega$	$1M\Omega < R \le 10M\Omega$			
	4			±100	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega {\le} R {\le} 1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$			
RTV0805	<u> </u>	400V	800V	. 200	1Ω≦R<10Ω	1Ω≦R<10Ω	1Ω≦R<10Ω			
	8			±200	1MΩ <r≦27mω< td=""><td>$1M\Omega < R \leq 27M\Omega$</td><td>1MΩ<r≦27mω< td=""></r≦27mω<></td></r≦27mω<>	$1M\Omega < R \leq 27M\Omega$	1MΩ <r≦27mω< td=""></r≦27mω<>			
	4			±100	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$			
RTV1206	$\frac{1}{4}$ W	500V	1000V	.000	1Ω≦R<10Ω	1Ω≦R<10Ω	1Ω≦R<10Ω			
				±200	$1M\Omega < R \leq 27M\Omega$	$1M\Omega < R \leq 27M\Omega$	1MΩ <r≦27mω< td=""></r≦27mω<>			
	4			±100	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega {\le} R {\le} 1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$			
RTV1210	<u>1</u> 2	-W 500V	V 500V	1000V	1000V	1000V	.000	1Ω≦R<10Ω	1Ω≦R<10Ω	1Ω≦R<10Ω
						±200	$1M\Omega < R \leq 27M\Omega$	$1M\Omega < R \leq 27M\Omega$	1MΩ <r≦27mω< td=""></r≦27mω<>	
	•			±100	$10\Omega{\leq}R{\leq}1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega{\leq}R{\leq}1M\Omega$			
RTV2010	<u>-3</u> W 4	500V	1000V	.000		1Ω≦R<10Ω	1Ω≦R<10Ω			
				±200		$1M\Omega < R \leq 10M\Omega$	$1M\Omega < R \le 10M\Omega$			
	1W			±100	$10\Omega{\leq}R{\leq}1M\Omega$	$10\Omega{\le}R{\le}1M\Omega$	$10\Omega{\leq}R{\leq}1M\Omega$			
RTV2512		W 500V	/ 1000V			1Ω≦R<10Ω	1Ω≦R<10Ω			
				±200		$1M\Omega < R \leq 10M\Omega$	$1M\Omega < R \le 10M\Omega$			
Operati	ng Tem	perature	Range		-5	5℃~+155℃				

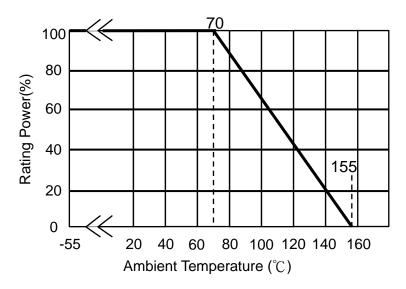




3.1 Power Derating Curve:

Operating Temperature Range : - 55~155 ℃

For resistors operated in ambient temperatures above 70°C, power rating shall be derated in accordance with figure below •



3.2 Voltage Rating:

Rated Voltage: The resistor shall have a DC continuous working voltage or a rms. AC continuous working voltage at commercial-line frequency and wave form corresponding to the power rating, as determined from the following:

$$E = \sqrt{R \times P}$$

E = Rated voltage (v)P= Power rating (w) R = Nominal resistance(Ω)

4 Dimensions:

								Unit:mm
ſ	0070	Туре	Dimension Size Code	L	w	Н	L1	L2
	Zŏ/3 *	RTV	0603	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.15	0.30±0.15
		RTV	0805	2.00±0.10	1.25±0.10	0.50±0.10	0.35±0.20	0.35±0.15
		RTV	1206	3.05±0.10	1.55±0.10	0.50±0.10	0.45±0.20	0.35±0.15
-=+==+ □□	· ── ── ─ ─ 」	RTV	1210	3.05±0.10	2.55±0.10	0.55±0.10	0.50±0.20	0.50±0.20
		RTV	2010	5.00±0.20	2.50±0.20	0.55±0.10	0.60±0.20	0.60±0.20
1 1		RTV	2512	6.30±0.20	3.20±0.20	0.55±0.10	0.60±0.20	0.69±0.20
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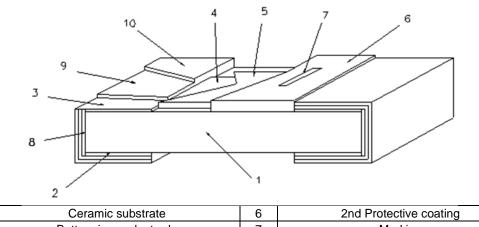
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5 Structure Graph:



1	Ceramic substrate	6	2nd Protective coating
2	Bottom inner electrode	7	Marking
3	Top inner electrode	8	Terminal inner electrode
4	Resistive layer	9	Ni plating
5	1st Protective coating	10	Sn plating

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6 Reliability Test:

6.1 Electrical Performance Test

Item	Conditions	Specifications
		Resistors
		Refer to item 3. general
	TCR (ppm/°C) = $R_1 (T_2 - T_1) \times 10^6$	specifications
Temperature	R1: Resistance at room temperature	
	R2: Resistance at -55° \mathbb{C} or +125° \mathbb{C}	
Coefficient of Resistance	T1: Room temperature	
Resistance	T2: Temperature -55 $^{\circ}$ C or +125 $^{\circ}$ C	
	Refer to JIS-C5201-1 4.8	
		0.5%
Short Time		5% : △R%=±2.0%
Insulation Resistance	rate. (Rated voltage refer to item 3. general specifications)	
	Refer to JIS-C5201-1 4.13	
	Put the resistor in the fixture, add 100 VDC in + ,- terminal for 60	≧10 ⁹ Ω
	sec then measured the insulation resistance between electrodes	
	and insulating enclosure or between electrodes and base material.	
	Refer to JIS-C5201-1 4.6	
	Metal block measuring Point A Metal plate measuring point B	
	Base material Insulating enclosure surface R0.5mm	
	Put the resistor in the fixture, add VAC (see spec. below) in +,-terminal for.	
Dielectric		appearance.
Withstand	RTV0805 • 1206 • 2010 • 2512 apply 500 VAC 1 minute.	
Voltage	RTV0603 apply 300 VAC 1 minute.	
	Refer to JIS-C5201-1 4.7	

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6.2 Mechanical Performance Test

Item	Conditions	Specifications
	Toot1. The register mounted on the board and in the board of the section for the	Resistors
	Test1:The resistor mounted on the board applied 5N pushing force	
Terminal	on the sample rear for 10 sec.	mechanical damage.
Strength	Test2:The resistor mounted on the board slowly add force on the	Test 2:F ≥ 5N
5.5	sample rear until the sample termination is breakdown.	
	Refer to JIS-C5201-1 4.16	
	The tested resistor be immersed into isopropyl alcohol of 20~25 $^\circ \! \mathbb{C}$	△R%=±0.5%
	for 5 minutes, then the resistor is left in the room for 48 hrs., and	
Resistance to	measured its resistance variance rate.	
Solvent		
	Refer to JIS-C5201-1 4.29 Preconditioning:	Solder opvorage over 05%
	Put the tested resistor in the apparatus of PCT, at a temperature	Solder coverage over 95%
	of 105° C, humidity of 100% RH, and pressure of 1.22×10^{5} Pa for	
	a duration of 4 hours. Then after left the tested resistor in room	
	temperature for 2 hours or more.	
Solderability	Test method:	
Concordonity	The resistor be immersed into solder pot in temperature $235\pm5^{\circ}$	
	for 2 sec, then the resistor is left as placed under microscope to	
	observed its solder area.	
	Refer to JIS-C5201-1 4.17	
		Test item 1:
	The tested resistor be immersed into molten solder of 260+5/-0 $^\circ\!\mathrm{C}$	(1).Variance rate on resistance
	for 10 seconds. Then the resistor is left in the room for 1 hour.	∆R%=±1.0%
	⊘Test method 2 (solder pot test):	Test item 2:
	The tested resistor be immersed into molten solder of 260+5/-0 $^{\circ}$ C	(1).Solder coverage over 95%
	for 30 seconds. Then the resistor is left as placed under	(2). The analonying material
Posistanas ta	microscope to observe its solder area.	(such as ceramic) shall no
Resistance to Soldering Heat		be visible at the crest corr
Coldening ried	◎Test method 3 (Electric iron test):	area of the electrode.
	Brobacting temperature : $250 \cdot 10^{\circ}$	Test item 3:
		(1).Variance rate on resistance
	Preheating the electric iron on electrode termination, as after that	$\wedge R\% = +1.0\%$
	step placed the iron over 60 min. and measured its resistance	
	variance rate.	
	Refer to JIS-C5201-1 4.18	



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Item Conditions Specifications Resistors ©Bending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTV0603 · 0805=5mm RTV1206 · 1210=3mm RTV2010 · 2512=2mm $\Delta R\%=\pm1.0\%$ Ioint Strength of Solder Image: Condition of the condition of th			
Item Conditions Resistors OBending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTV0603 \ 0805=5mm RTV1206 \ 1210=3mm RTV2010 \ 2512=2mm △R%=±1.0% Joint Strength of Solder			
Image: Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTV0603 \ 0.805=5mm AR%=±1.0% D:RTV1206 \ 1210=3mm RTV12010 \ 2512=2mm Image: Strength of Solder Image	Itom	Conditions	
Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTV0603 \ 0805=5mm RTV1206 \ 1210=3mm RTV2010 \ 2512=2mm Noint Strength of Solder	nem	Conditions	Resistors
Joint Strength of Solder		Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RTV0603 \ 0805=5mm RTV1206 \ 1210=3mm RTV2010 \ 2512=2mm	∆R%=±1.0%
Refer to JIS-C5201-1 4.33	oint Strength of Solder	45 45 Chip realstor Chip realstor Preseturize (Arrount of band) OHM Meter	
		Pater to US-C5201-1 4 33	

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6.3 Environmental Test

ltom		Conditions			Specifications
Item		Conditions)		Resistors
Resistance to Dry Heat	Refer to JIS-C5201-1 4.25				0.5%
	Put the which s consecu	tested resistor in the chamber hown in the following table sha utively. Then leaving the tested ature for 1 hours, and measure	all be repeated 300 tir d resistor in the room	nes	0.5%、1%:△R%=±0.5% 5%:△R%=±1.0%
Thermal Shock		Testing Cond	tion		
		Lowest Temperature	-55±5 ℃		
		Highest Temperature	125±5 ℃		
		Temperature-retaining time	15 minutes each		
	Refer to	MIL-STD 202 Method 107			
Loading Life in Moisture	relative minutes tested re its resis	tested resistor in the chamber humidity 90~95% and load the on, 30 minutes off, total 1000 esistor in room temperature fo tance variance rate.	the	0.5%	
Load Life	Refer to JIS-C5201-1 4.24 Put the tested resistor in chamber under temperature 70±2°C and load the rated voltage for 90 minutes on, 30 minutes off, tota 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25				0.5% 、1%:∆R%=±2.0% 5%:∆R%=±3.0%

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7 Measurement Point:

Bottom electrode				Unit : mm
A	- -1	DIM TYPE	Α	В
	-+	RTV0603	1.35±0.05	0.35±0.05
0		RTV0805	1.80±0.05	0.35±0.05
Θ		RTV1206	2.90±0.05	0.35±0.05
		RTV1210	2.90±0.05	0.35±0.05
\odot Current Terminal		RTV2010	4.50±0.05	1.15±0.05
O Voltage Terminal		RTV2512	5.90±0.05	1.60±0.05

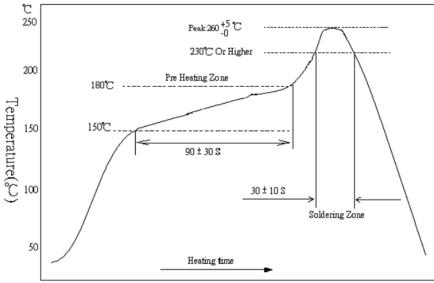
8 Plating Thickness:

- 8.1 Ni: \geq 2 μ m
- 8.2 Sn(Tin):≧3µm
- 8.3 Sn(Tin): Matte Sn

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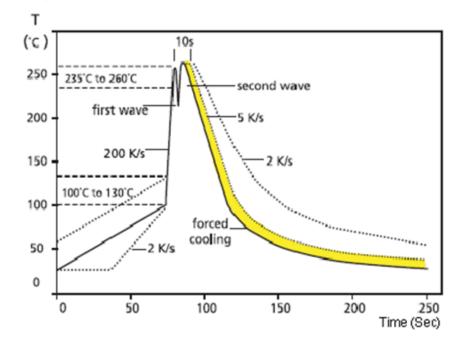


- 9 Technical application notes: (This is for recommendation, please customer perform adjustment according to actual application)
 - 9.1 Recommend Soldering Method:
 - 9.1.1 Lead Free IR Reflow Soldering Profile (MEET J-STD-020D)



Remark: The peak temperature of soldering heat is 260 +5/-0 $\,\,^\circ\!\mathrm{C}\,$ for 10 seconds

9.1.2 Lead Free Double-Wave Soldering Profile.(This applies to 0603 size inclusive above products)



9.1.3 Soldering Iron: temperature $350^{\circ}C \pm 10^{\circ}C$, dwell time shall be less than 3 sec.

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I Init mm

9.2 Recommend Land Pattern Design (For Reflow Soldering):

When a component is soldered, the resistance after soldering changes slightly depending on the size of the soldering area and the amount of soldering. When designing a circuit, it is necessary to consider the effect of a decrease or increase in its resistance.

	Unit.min		Juri. Thu	
	DIM TYPE	Α	В	С
	RTV0603	0.8	2.1	0.9
	RTV0805	1.2	3.0	1.3
A	RTV1206	2.2	4.2	1.6
B	RTV1210	2.2	4.2	2.8
 ₽	RTV2010	3.5	6.1	2.8
	RTV2512	3.8	8.0	3.5

9.3 Environment Precautions:

This specification product is for general electronic use, ABCO will not be responsible for any damage, cost or loss caused by using this specification product in any special environment. If other applications need to confirm with ABCO.

If consumer intends to use our Company product in special environment or condition (including but not limited to those mentioned below), then will need to make individual recognition of product features and reliability accordingly.

- (a) Used in high temperature and humidity environment
- (b) Exposed to sea breeze or other corrosive gas, such as Cl2 > H2S > NH3 > SO2 and NO2.
- (c) Used in non-verified liquids including water, oil, chemical and organic solvents.
- (d) Using non-verified resin or other coating material to seal or coat our Company product.
- (e) After soldering, it is necessary to use water-soluble detergents to clean residual solder fluxes, even though no-clean fluxes are recommended.

9.4 Momentary Overload Precautions:

The product might be out of function when momentary overloaded. Please make sure to avoid momentary overloading while using and preserving.

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9.5 Operation and Processing Precautions:

- (a) Avoid damage to the edge of resistor and protective layer caused by mechanical stress.
- (b) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
- (c) Make sure the power rating is under the limit when using the resistor. When power rating is over the limit, the resister will be overloaded. There might be machinery damage due to the climbing temperature.
- (d) If the resister will be exposed under massive impact load (shock wave) in a short period of time, the working environment must be set up well before use.
- (e) Please make evaluation and confirmation when the product is well used in your company and have a through consideration of it's fail-safe design to ensure the system safety.

10 Storage and transportation requirement:

- 10.1 The temperature condition must be controlled at 25±5℃, the R.H. must be controlled at 60±15%. The stock can maintain quality level in two years.
- 10.2 Please avoid the mentioned harsh environment below when storing to ensure product performance and its' weldability. Places exposed to sea breeze or other corrosive gas, such as Cl2 \ H2S \ NH3 \ SO2 and NO2.
- 10.3 When the product is moved and stored, please ensure the correct orientation of the box. Do not drop or squeeze the box. Otherwise, the electrode or the body of the product may be damaged.

11 The carton packaged for electronic-information products is made by the symbol as follows: (For china)

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Marking for control of pollution cause by electronic-information products	Marking for package recovery

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